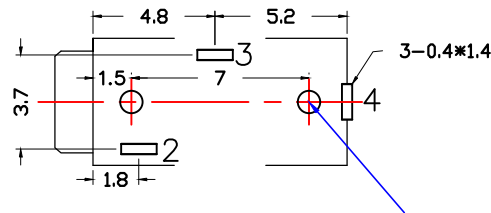
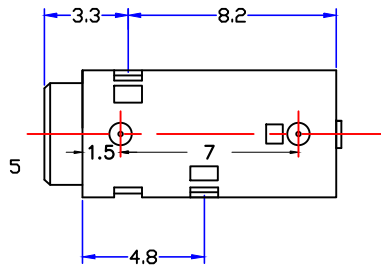
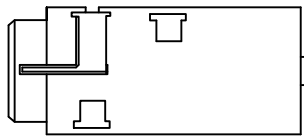
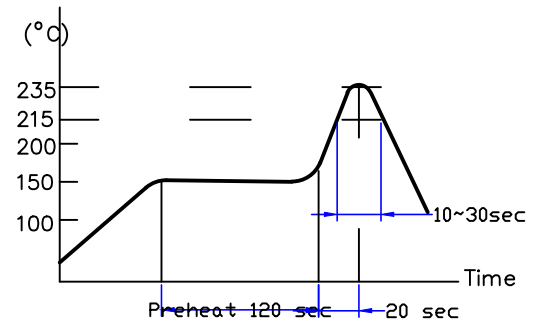


SCHMATIC



P.C.B TERMINAL POSITION



REFLOW SOLDERING CONDITIONS

No	Parts	Material	Qty	Finish	Specifications	PJ-202-H
1	Body	PA66+30%Fiber	1	94V-0	Rating: DC 12V 1A	TITLE: PHONE JACK
2	Chip Terminal	t:0.2 Cu-Ti Alloy	1	Ep-Cu/Ni 1,Ag 1(Silver Plating)	Contact Resistance: 30m ohm max	UNLESS OTHERWISE SPECIFIED TOLERANCE ±0.1 ANGLE TOL ±30"
3	Ring Terminal	t:0.2 Cu-Ti Alloy	1	Ep-Cu/Ni 1,Ag 1(Silver Plating)	Insulation Resistance: 100M ohm at 500V AC	
4	Ring Terminal	t:0.2 Cu-Ti Alloy	1	Ep-Cu/Ni 1,Ag 1(Silver Plating)	Dielectric Strength: AC 500V for 1 Minute	
					Insertion & Extraction Force: 3-1.5kgf	
					Life: 5.000 Cycles	UNIT: mm SCALE:
					Taping: 1.000 Pcs/Reel	DRAWN: Aijw
						DATE: 2005/12/14
						CHECKED:
						DATE:
						APPROVED:
						DATE:

